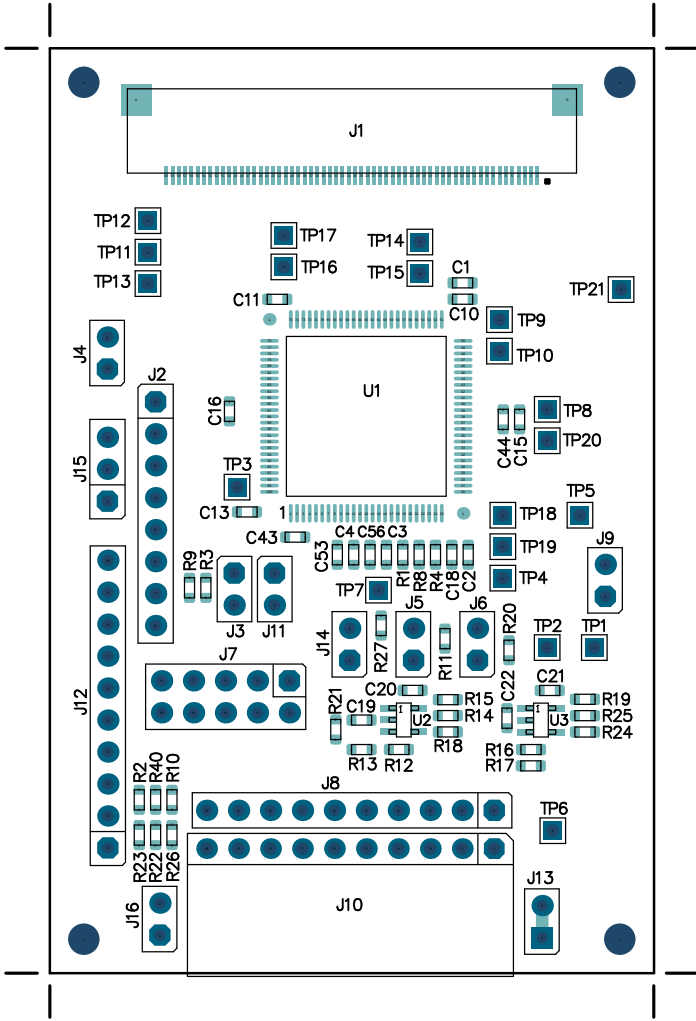


REV	ECO	Comments	Date
A0	N/A	First Issue	24th Jan 2014
A1	N/A	Silkscreen update to mXTxxxT-AT	23rd Feb 2015
A2	N/A	Removed short on top layer Gerber files	5th Oct 2015
B0	N/A	Prox removed, SPI & test points added	14th Mar 2017
B1	N/A	J15 added	17th May 2017
B2	N/A	RoHS, CE & WEEE symbols added	29th Mar 2018
1	N/A	Updated to MCL, IC pinout fixed, PCB no. changed, UKCA mark added	4th Oct 2022

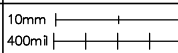


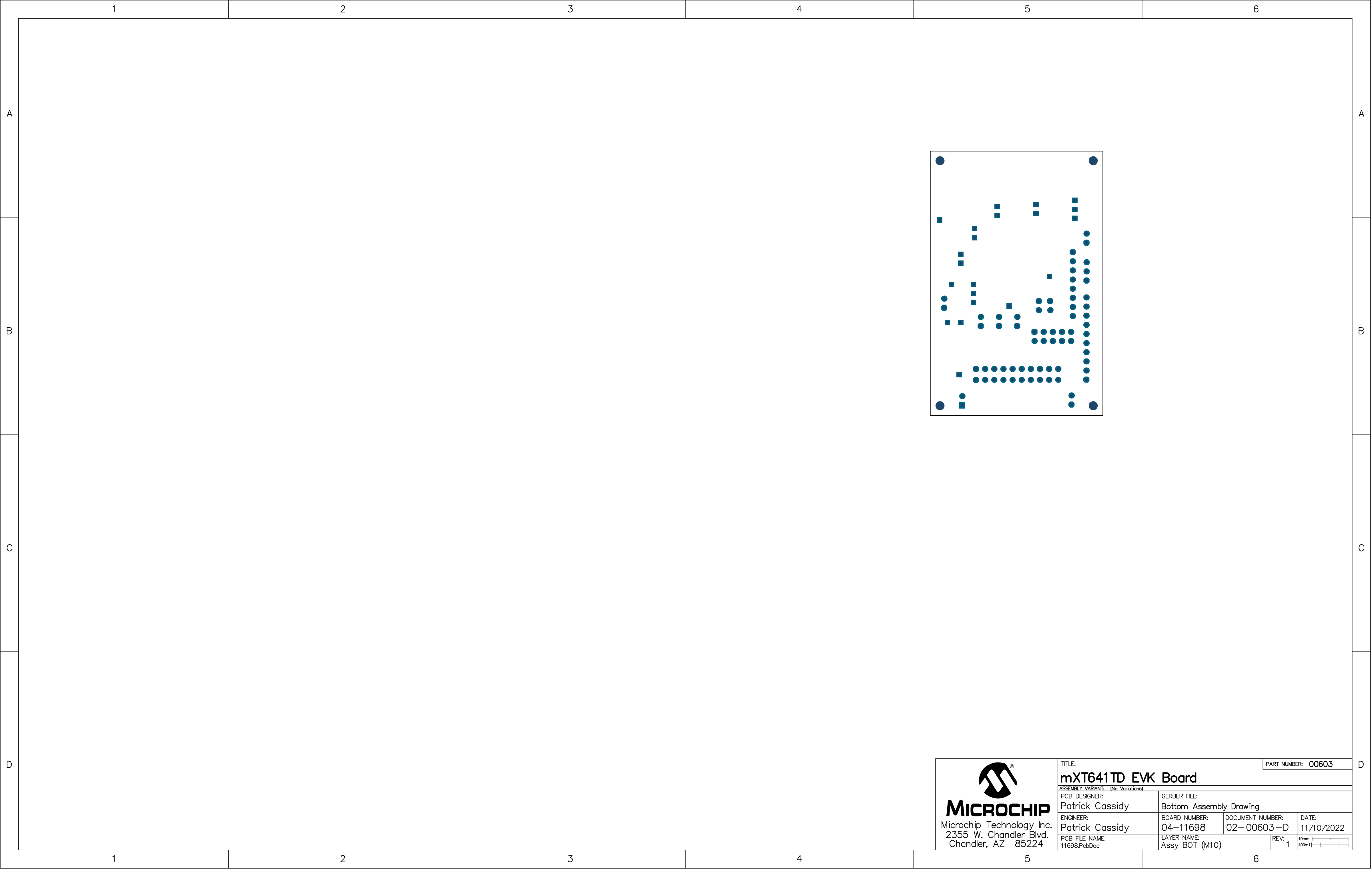
ASSEMBLY NOTES:

1. ALL COMPONENTS SHALL BE RoHS COMPLIANT.
2. ALL UNUSED THROUGH HOLE COMPONENT LOCATIONS SHALL BE FREE OF SOLDER.
3. ALL TEST POINT THROUGH HOLES (DENOTED TPxx) SHALL BE FREE OF SOLDER.
4. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD, EXCEPT AS NOTED.
5. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
6. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM HEIGHT OF 2mm.
7. PLACE LABELS ON THE LOCATION INDICATED.



MICROCHIP
Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE: mXT641TD EVK Board				PART NUMBER: 00603	
ASSEMBLY VARIANT: (No Variations)					
PCB DESIGNER: Patrick Cassidy		GERBER FILE: Top Assembly Drawing			
ENGINEER: Patrick Cassidy		BOARD NUMBER: 04-11698	DOCUMENT NUMBER: 02-00603-D	DATE: 11/10/2022	
PCB FILE NAME: 11698.PcbDoc		LAYER NAME: Assy TOP (M11)		REV: 1	





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Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE:		PART NUMBER: 00603		
mXT641TD EVK Board				
ASSEMBLY VARIANT: (No Variations)				
PCB DESIGNER: Patrick Cassidy		GERBER FILE: Bottom Assembly Drawing		
ENGINEER: Patrick Cassidy		BOARD NUMBER: 04-11698	DOCUMENT NUMBER: 02-00603-D	DATE: 11/10/2022
PCB FILE NAME: 11698.PcbDoc		LAYER NAME: Assy BOT (M10)		REV: 1
		